Video Amplifier

The NE592 is a monolithic, two-stage, differential output, wideband video amplifier. It offers fixed gains of 100 and 400 without external components and adjustable gains from 400 to 0 with one external resistor. The input stage has been designed so that with the addition of a few external reactive elements between the gain select terminals, the circuit can function as a high-pass, low-pass, or band-pass filter. This feature makes the circuit ideal for use as a video or pulse amplifier in communications, magnetic memories, display, video recorder systems, and floppy disk head amplifiers. Now available in an 8-pin version with fixed gain of 400 without external components and adjustable gain from 400 to 0 with one external resistor.

Features

- 120 MHz Unity Gain Bandwidth
- Adjustable Gains from 0 to 400
- Adjustable Pass Band
- No Frequency Compensation Required
- Wave Shaping with Minimal External Components
- MIL-STD Processing Available
- Pb-Free Packages are Available

Applications

- Floppy Disk Head Amplifier
- Video Amplifier
- Pulse Amplifier in Communications
- Magnetic Memory
- Video Recorder Systems

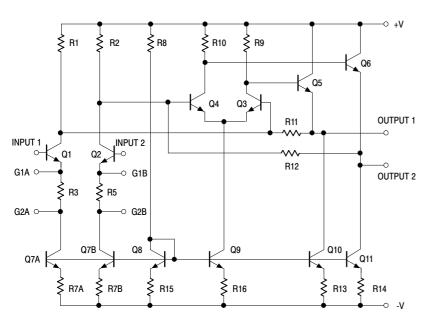


Figure 1. Block Diagram



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MARKING DIAGRAMS



SOIC-8 **D SUFFIX CASE 751**















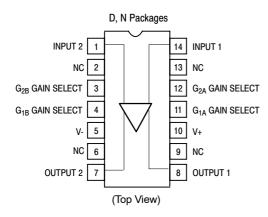
= Assembly Location L, WL = Wafer Lot Y. YY = Year

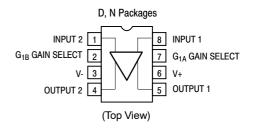
W, WW = Work Week ■ or G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

PIN CONNECTIONS





MAXIMUM RATINGS ($T_A = +25^{\circ}C$, unless otherwise noted.)

Rating	Symbol	Value	Unit	
Supply Voltage		V _{CC}	±8.0	V
Differential Input Voltage		V _{IN}	±5.0	V
Common-Mode Input Voltage		V _{CM}	±6.0	V
Output Current		I _{OUT}	10	mA
Operating Ambient Temperature Range		T _A	0 to +70	°C
Operating Junction Temperature		TJ	150	°C
Storage Temperature Range		T _{STG}	65 to +150	°C
Maximum Power Dissipation, T _A = 25°C (Still Air) (Note 1)	D-14 Package D-8 Package N-14 Package N-8 Package	P _{D MAX}	0.98 0.79 1.44J1.17	W
Thermal Resistance, Junction-to-Ambient	D-14 Package D-8 Package N-14 Package N-8 Package	$R_{ hetaJA}$	145 182 100 130	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Derate above 25°C at the following rates:

D-14 package at 6.9 mW/°C

D-8 package at 5.5 mW/°C

N-14 package at 10 mW/°C N-8 package at 7.7 mW/°C.

DC ELECTRICAL CHARACTERISTICS ($V_{SS} = \pm 6.0 \text{ V}$, $V_{CM} = 0$, typicals at $T_A = +25^{\circ}\text{C}$, min and max at $0^{\circ}\text{C} \le T_A \le 70^{\circ}\text{C}$, unless otherwise noted. Recommended operating supply voltages $V_S = \pm 6.0 \text{ V}$.)

Characteristic	Test Conditions	Symbol	Min	Тур	Max	Unit
Differential Voltage Gain Gain 1 (Note 2) Gain 2 (Notes 3 and 4)	$R_L = 2.0 \text{ k}\Omega, V_{OUT} = 3.0 V_{P-P}$	A _{VOL}	250 80	400 100	600 120	V/V
Input Resistance Gain 1 (Note 2) Gain 2 (Notes 3 and 4)	$T_{A} = 25^{\circ}C$ $0^{\circ}C \le T_{A} \le 70^{\circ}C$	R _{IN}	_ 10 8.0	4.0 30 -	- - -	kΩ
Input Capacitance	Gain 2 (Note 4)	C _{IN}	-	2.0	_	pF
Input Offset Current	$T_A = 25^{\circ}C$ $0^{\circ}C \le T_A \le 70^{\circ}C$	los	_ _	0.4	5.0 6.0	μΑ
Input Bias Current	$T_A = 25^{\circ}C$ $0^{\circ}C \le T_A \le 70^{\circ}C$	I _{BIAS}		9.0	30 40	μΑ
Input Noise Voltage	BW 1.0 kHz to 10 MHz	V _{NOISE}	-	12	-	μV_{RMS}
Input Voltage Range	-	V _{IN}	±1.0	-	-	V
Common-Mode Rejection Ratio Gain 2 (Note 4)	$\begin{array}{c} V_{CM} \pm 1.0 \text{ V, } f < 100 \text{ kHz, } T_A = 25^{\circ}\text{C} \\ V_{CM} \pm 1.0 \text{ V, } f < 100 \text{ kHz,} \\ 0^{\circ}\text{C} \leq T_A \leq 70^{\circ}\text{C} \\ V_{CM} \pm 1.0 \text{ V, } f < 5.0 \text{ MHz} \end{array}$	CMRR	60 50	86 - 60	_ _	dB
Supply Voltage Rejection Ratio Gain 2 (Note 4)	$\Delta V_{S} = \pm 0.5 \text{ V}$	PSRR	50	70	-	dB
Output Offset Voltage Gain 1 Gain 2 (Note 4) Gain 3 (Note 5) Gain 3 (Note 5)	$R_{L} = \infty$ $R_{L} = \infty$ $R_{L} = \infty, T_{A} = 25^{\circ}C$ $R_{L} = \infty, 0^{\circ}C \le T_{A} \le 70^{\circ}C$	V _{OS}	- - - -	- - 0.35 -	1.5 1.5 0.75 1.0	V
Output Common-Mode Voltage	R _L = ∞, T _A = 25°C	V _{CM}	2.4	2.9	3.4	V
Output Voltage Swing Differential	$R_L = 2.0 \text{ k}\Omega, T_A = 25^{\circ}\text{C}$ $R_L = 2.0 \text{ k}\Omega, 0^{\circ}\text{C} \le T_A \le 70^{\circ}\text{C}$	V _{OUT}	3.0 2.8	4.0 -	-	V
Output Resistance	-	R _{OUT}	-	20	-	Ω
Power Supply Current	$\begin{aligned} R_L &= \infty, T_A = 25^{\circ}C \\ R_L &= \infty, 0^{\circ}C \leq T_A \leq 70^{\circ}C \end{aligned}$	I _{CC}	- -	18 -	24 27	mA

$\textbf{AC ELECTRICAL CHARACTERISTICS} \ (T_{A} = +25^{\circ}C \ V_{SS} = \\ \pm 6.0 \ V, \ V_{CM} = 0, \ unless \ otherwise \ noted. \ Recommended \ operating$ supply voltages $V_S = \pm 6.0 \text{ V.}$)

Characteristic	Test Conditions	Symbol	Min	Тур	Max	Unit
Bandwidth	-	BW				MHz
Gain 1 (Note 2)			_	40	_	
Gain 2 (Notes 3 and 4)			_	90	_	
Rise Time		t _R				ns
Gain 1 (Note 2)	$V_{OUT} = 1.0 V_{P-P}$		-	10.5	12	
Gain 2 (Notes 3 and 4)			-	4.5	_	
Propagation Delay		t _{PD}				ns
Gain 1 (Note 2)	$V_{OUT} = 1.0 V_{P-P}$		-	7.5	10	
Gain 2 (Notes 3 and 4)			_	6.0	_	

- Gain select Pins G_{1A} and G_{1B} connected together.
 Gain select Pins G_{2A} and G_{2B} connected together.
 Applies to 14-pin version only.
 All gain select pins open.

TYPICAL PERFORMANCE CHARACTERISTICS

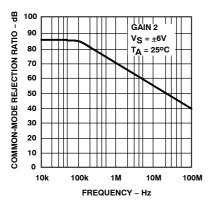


Figure 2. Common-Mode Rejection Ratio as a Function of Frequency

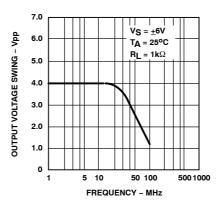


Figure 3. Output Voltage Swing as a Function of Frequency

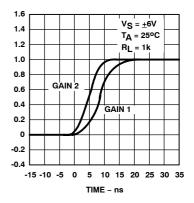


Figure 4. Pulse Response

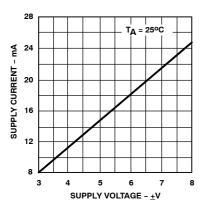


Figure 5. Supply Current as a Function of Temperature

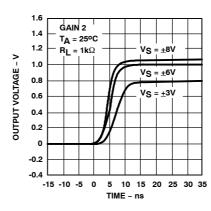


Figure 6. Pulse Response as a Function of Supply Voltage

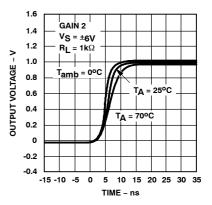


Figure 7. Pulse Response as a Function of Temperature

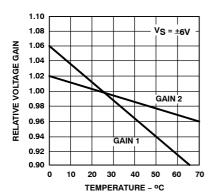


Figure 8. Voltage Gain as a Function of Temperature

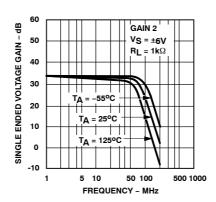


Figure 9. Gain vs. Frequency as a Function of Temperature

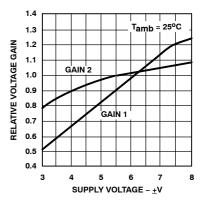


Figure 10. Voltage Gain as a Function of Supply Voltage

TYPICAL PERFORMANCE CHARACTERISTICS

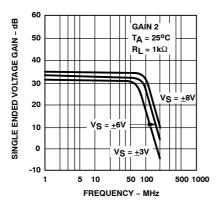


Figure 11. Gain vs. Frequency as a Function of Supply Voltage

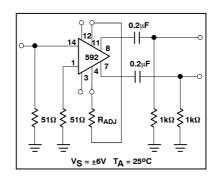


Figure 12. Voltage Gain Adjust Circuit

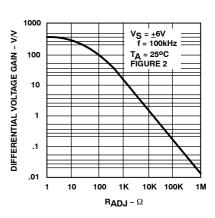


Figure 13. Voltage Gain as a Function of RADJ (Figure 2)

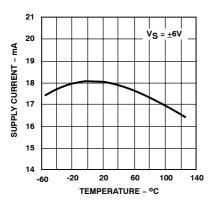


Figure 14. Supply Current as a Function of Temperature

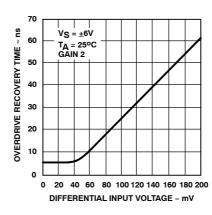


Figure 15. Differential Overdrive Recovery Time

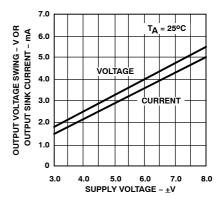


Figure 16. Output Voltage and Current Swing as a Function of Supply Voltage

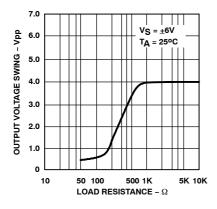


Figure 17. Output Voltage Swing as a Function of Load Resistance

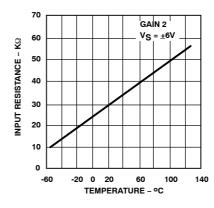


Figure 18. Input Resistance as a Function of Temperature

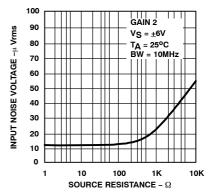


Figure 19. Input Noise Voltage as a Function of Source Resistance

TYPICAL PERFORMANCE CHARACTERISTICS

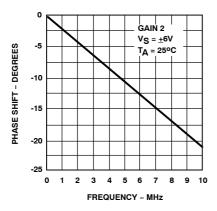


Figure 20. Phase Shift as a Function of Frequency

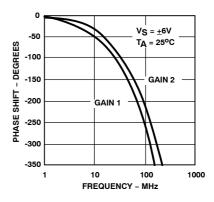


Figure 21. Phase Shift as a Function of Frequency

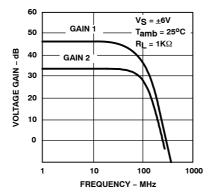


Figure 22. Voltage Gain as a Function of Frequency

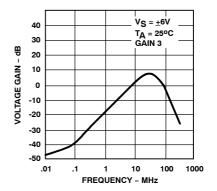


Figure 23. Voltage Gain as a Function of Frequency

TEST CIRCUITS ($T_A = 25$ °C, unless otherwise noted.)

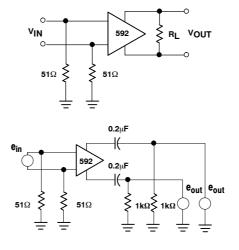


Figure 24. Test Circuits

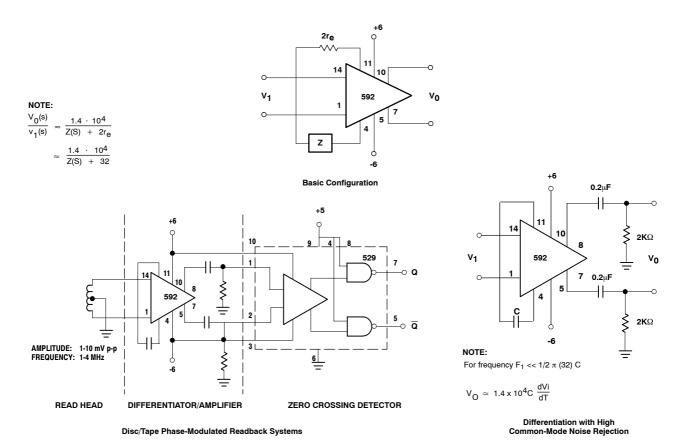


Figure 25. Typical Applications

Z NETWORK	FILTER TYPE	V ₀ (s) TRANSFER V ₁ (s) FUNCTION
R L	LOW PASS	$\frac{1.4 \times 10^4}{L} \left[\frac{1}{s + R/L}\right]$
R C ○	HIGH PASS	$\frac{1.4 \times 10^4}{R} \left[\frac{s}{s + 1/RC} \right]$
R L C	BAND PASS	$\frac{1.4 \times 10^4}{L} \left[\frac{s}{s^2 + R/Ls + 1/LC} \right]$
R C C	BAND REJECT	$\frac{1.4 \times 10^{4}}{R} \left[\frac{s^{2} + 1/LC}{s^{2} + 1/LC + s/RC} \right]$

NOTES:

In the networks above, the R value used is assumed to include $2r_{\text{e}},$ or approximately 32 Ω . S = $j\Omega$ Ω = $2\pi f$

Figure 26. Filter Networks

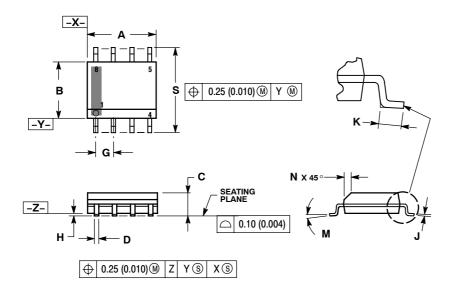
ORDERING INFORMATION

Device	Temperature Range	Package	Shipping [†]
NE592D8		SOIC-8	
NE592D8G		SOIC-8 (Pb-Free)	98 Units/Rail
NE592D8R2		SOIC-8	
NE592D8R2G		SOIC-8 (Pb-Free)	2500 / Tape & Reel
NE592N8	7	PDIP-8	
NE592N8G		PDIP-8 (Pb-Free)	50 Units/Rail
NE592D14	0 to +70°C	SOIC-14	
NE592D14G		SOIC-14 (Pb-Free)	55 Units/Rail
NE592D14R2	7	SOIC-14	
NE592D14R2G		SOIC-14 (Pb-Free)	2500 / Tape & Reel
NE592N14	1	PDIP-14	
NE592N14G		PDIP-14 (Pb-Free)	25 Units/Rail

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

PACKAGE DIMENSIONS

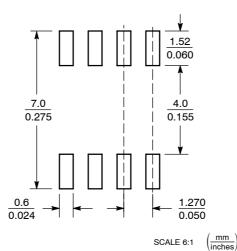
SOIC-8 NB CASE 751-07 **ISSUE AH**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.80	5.00	0.189	0.197
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27	7 BSC	0.050 BSC	
Н	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
М	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

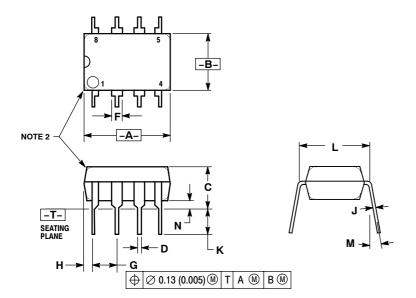
SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

PDIP-8 **N SUFFIX** CASE 626-05 ISSUE L

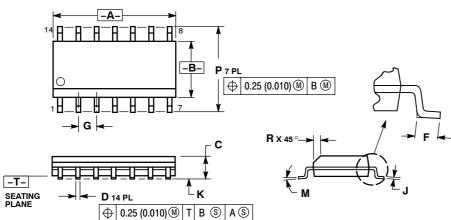


- NOTES:
 1. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 2. PACKAGE CONTOUR OPTIONAL (ROUND OR SQUARE CORNERS).
 3. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.40	10.16	0.370	0.400
В	6.10	6.60	0.240	0.260
С	3.94	4.45	0.155	0.175
D	0.38	0.51	0.015	0.020
F	1.02	1.78	0.040	0.070
G	2.54	BSC	0.100) BSC
Н	0.76	1.27	0.030	0.050
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300	BSC
M		10°		10°
N	0.76	1.01	0.030	0.040

PACKAGE DIMENSIONS

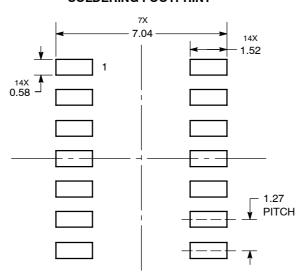
SOIC-14 CASE 751A-03 **ISSUE H**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
7	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
М	0 °	7 °	0 °	7 °
Р	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

SOLDERING FOOTPRINT*

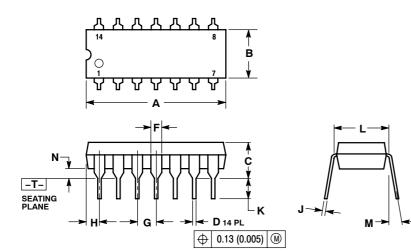


DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

PDIP-14 CASE 646-06 ISSUF P



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIMENSION B DOES NOT INCLUDE MOLD FLASH.
- 5. ROUNDED CORNERS OPTIONAL.

INCHES		MILLIM	IETERS
MIN	MAX	MIN	MAX
0.715	0.770	18.16	19.56
0.240	0.260	6.10	6.60
0.145	0.185	3.69	4.69
0.015	0.021	0.38	0.53
0.040	0.070	1.02	1.78
0.100 BSC		2.54 BSC	
0.052	0.095	1.32	2.41
0.008	0.015	0.20	0.38
0.115	0.135	2.92	3.43
0.290	0.310	7.37	7.87
	10 °		10 °
0.015	0.039	0.38	1.01
	MIN 0.715 0.240 0.145 0.015 0.040 0.100 0.052 0.008 0.115 0.290	MIN MAX 0.715 0.770 0.240 0.260 0.145 0.185 0.015 0.021 0.040 0.070 0.100 BSC 0.052 0.095 0.008 0.015 0.115 0.135 0.290 0.310 10 °	MIN MAX MIN 0.715 0.770 18.16 0.240 0.260 6.10 0.145 0.185 3.69 0.015 0.021 0.38 0.040 0.070 1.02 0.100 BSC 2.54 0.052 0.095 1.32 0.008 0.015 0.20 0.115 0.20 0.135 0.290 0.310 7.37 10°

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